# R6049YNX3

# Nch 600V 68mohm(typ) Power MOSFET

Datasheet

$V_{DSS}(@Tj max.)^{*5}$	650V
$R_{DS(on)}(Max.)$	82mΩ
I <sub>DP</sub> *2	±147A
P <sub>D</sub>	448W

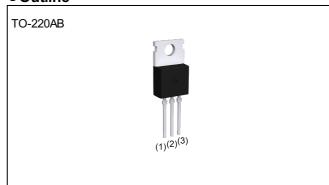
### Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Drive circuits can be simple
- 4) Pb-free plating; RoHS compliant
- 5) Halogen free mold compound

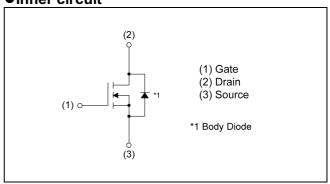
# Application

Switching applications

# Outline



# •Inner circuit



Marking	R6049YNX3
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# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	600	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±49	Α
Pulsed drain current	I <sub>DP</sub> *2	±147	А
Gate - Source voltage	V <sub>GSS</sub>	±30	V
Avalanche current, single pulse	I <sub>AS</sub>	2.8	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	208	mJ
MOSFET dv/dt	dv/dt*4	120	V/ns
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	448	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# ●Thermal resistance

Daramatar	C. mak al	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	0.28	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	62.5	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Uniil
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	600	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V	-	-	100	μΑ
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30 V, V_{DS} = 0 V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 2.9 \text{mA}$	4	5	6	V
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 12V, I <sub>D</sub> = 11A	-	68	82	mΩ
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 11A	-	70	84	mΩ
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	1.0	-	Ω

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Currente e l	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 100V	-	2940	-	
Output capacitance	C <sub>oss</sub>	f = 100kHz	-	100	-	
Effective output capacitance energy related	C <sub>o(er)</sub> *6	V <sub>GS</sub> = 0V	-	100	-	pF
Effective output capacitance time related	C <sub>o(tr)</sub> *7	V <sub>DS</sub> = 0V to 480V	-	650	1	
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ 300V, V <sub>GS</sub> = 12V	-	38	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 11A	-	33	-	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ~ 27Ω	-	91	-	ns
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	19	-	

# • Gate charge characteristics ( $T_a = 25$ °C)

Darameter	Cumb al	Conditions	Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≈ 300V	-	65	1	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 11A	-	21	1	nC
Gate - Drain charge	$Q_{gd}^{*5}$	V <sub>GS</sub> = 10V	-	30	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 300V$ , $I_D = 11A$	-	7	-	V

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Daramatar	Cumph of	Conditions	Values			Unit	
Parameter 	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I <sub>S</sub> *1	T <sub>C</sub> = 25°C	-	-	49	Α	
Pulsed source current	l <sub>SP</sub> *2		-	-	147	Α	
Source-Drain voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 11A	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5	V <sub>DD</sub> ≈ 400V	-	380	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	I <sub>S</sub> = 11A	-	6.5	-	μC	
Peak reverse recovery current	<sub>rr</sub> *5	di/dt = 100A/μs	-	34	-	Α	

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 50mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , starting T<sub>j</sub>=25°C

<sup>\*4</sup>  $V_{DS} = 0$  to 400V

<sup>\*5</sup> Pulsed

<sup>\*6</sup> Co(er) is a fixed capacitance that gives the same stored energy as Coss while V<sub>DS</sub> is rising from 0 to 80% V<sub>DSS</sub>.

<sup>\*7</sup> Co(tr) is a fixed capacitance that gives the same charging time as Coss while V<sub>DS</sub> is rising from 0 to 80% V<sub>DSS</sub>.

Fig.1 Power Dissipation Derating Curve

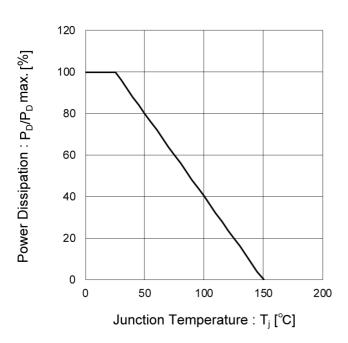


Fig.2 Drain Current Derating
Curve vs. Junction Temperature

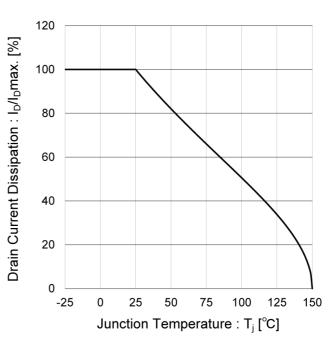


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

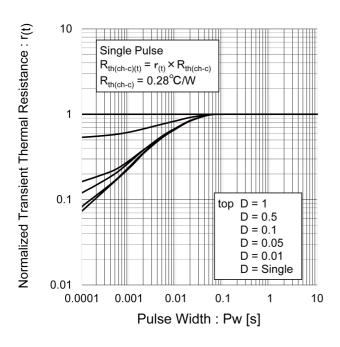


Fig.4 Maximum Safe Operating Area

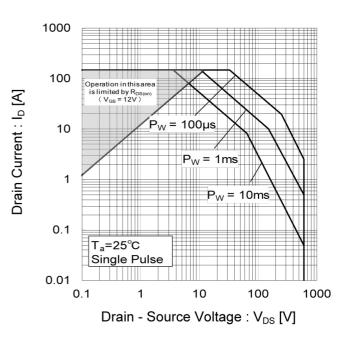


Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

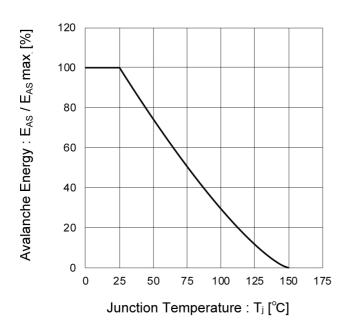


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

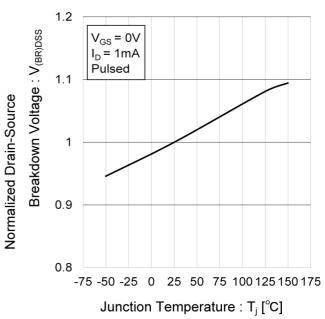


Fig.7 Typical Output Characteristics(I)

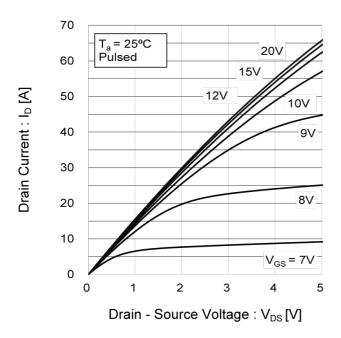


Fig.8 Typical Output Characteristics(II)

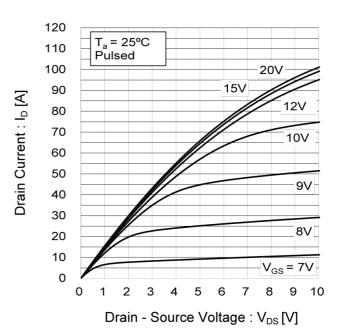


Fig.9 Typical Transfer Characteristics

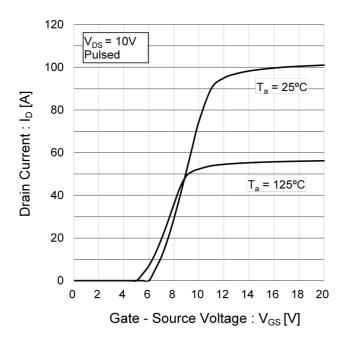


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

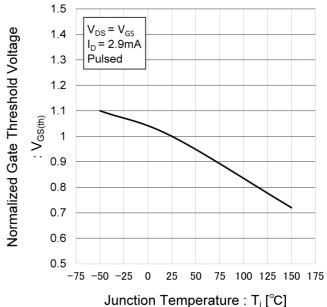


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

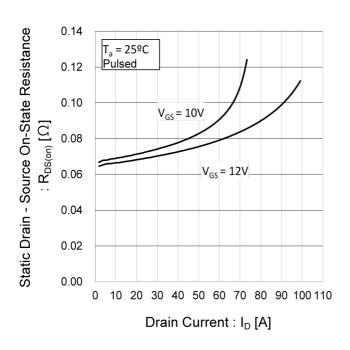


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

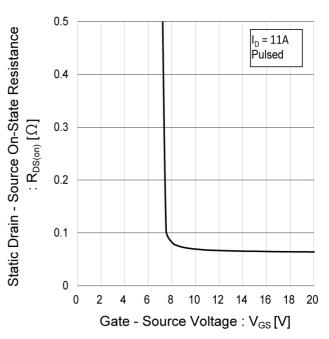


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

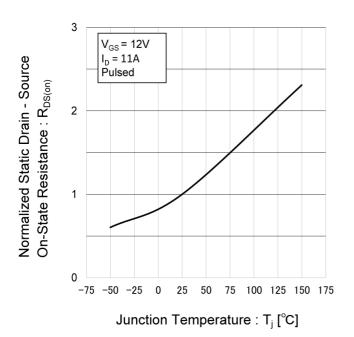


Fig.14 Capacitances

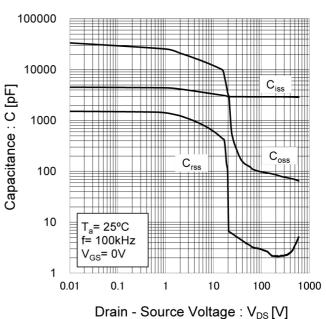


Fig.15 Coss Stored Energy

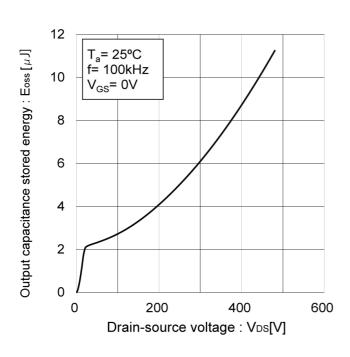


Fig.16 Gate charge

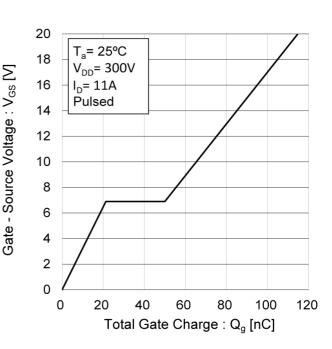
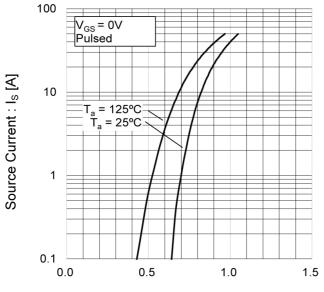
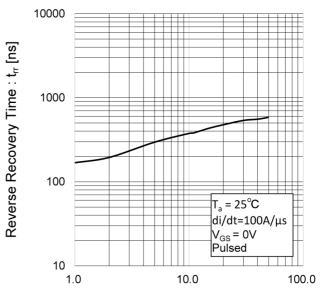


Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage :  $V_{\text{SD}}$  [V]

Fig.18 Reverse Recovery Time vs. Source Current



# Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

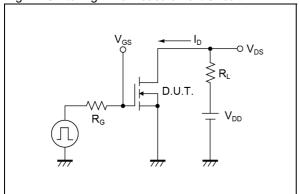


Fig.2-1 Gate Charge Measurement Circuit

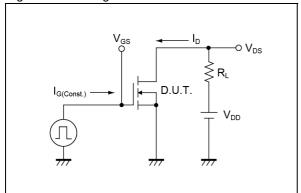


Fig.3-1 Avalanche Measurement Circuit

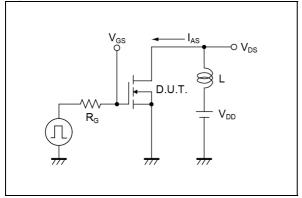


Fig.4-1 trr Measurement Circuit

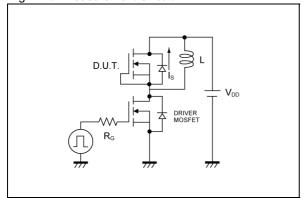


Fig.1-2 Switching Waveforms

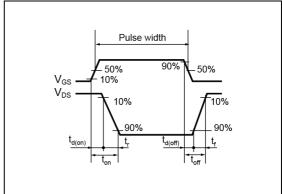


Fig.2-2 Gate Charge Waveform

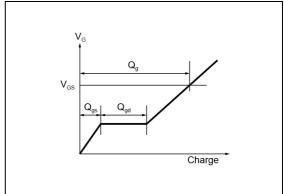


Fig.3-2 Avalanche Waveform

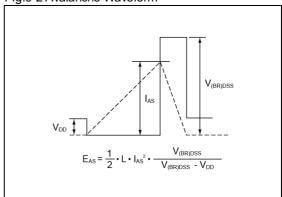
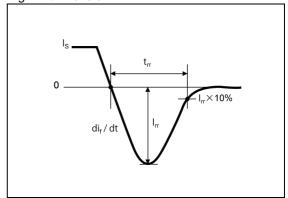
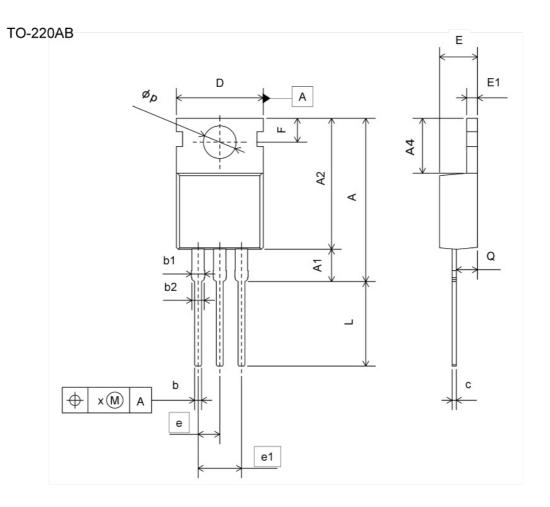


Fig.4-2 trr Waveform



# Dimensions



DIM	MILIME	TERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	18.30	20.00	0.720	0.787
A1	3.60	4.00	0.142	0.157
A2	14.70	16.00	0.579	0.630
A4	6.30	6.60	0.248	0.260
b	0.65	0.95	0.026	0.037
b1	1.20	1.75	0.047	0.069
b2	1.20	1.70	0.047	0.067
С	0.35	0.65	0.014	0.026
D	9.96	10.36	0.392	0.408
E	4.24	4.64	0.167	0.183
E1	1.14	1.40	0.045	0.055
е	2.	54	0.1	00
e1	5.	5.08		200
F	2.60	3.00	0.102	0.118
L	9.47	10.37	0.373	0.408
$\phi$ p	3.69	3.99	0.145	0.157
Q	2.30	2.70	0.091	0.106
Х	-0	0.38	-	0.015

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГУООШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

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  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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